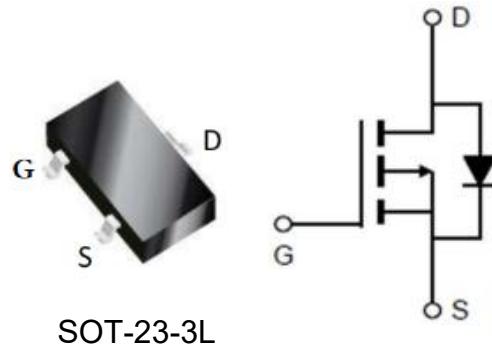


### Features

- ◆ -30V, -4A,  $R_{DS(ON)}$ (Typ.)=39mΩ@ $V_{GS} = -10V$ .
- ◆ This device is suitable for use as a load switch or other general applications.
- ◆ RoHS and Halogen-Free Compliant.



### Absolute Maximum Ratings $T_c = 25^\circ C$ unless otherwise noted

Symbol	Parameter	Limit	Unit
$V_{DS}$	Drain-Source Voltage	-30	V
$V_{GS}$	Gate-Source Voltage	± 12	
$I_D$	Drain Current-Continuous, $T_A = 25^\circ C$	-4	A
$I_{DM}$	Drain Current-Pulsed <sup>b</sup>	-27	
$P_D$	Maximum Power Dissipation @ $T_A = 25^\circ C$	1.4	W
$T_{STG}$	Store Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient Max <sup>a</sup>	125	°C/W

### Electrical Characteristics $T_J = 25^\circ C$ unless otherwise noted

#### Off Characteristics

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = -250\mu A$	-30	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = -30V, V_{GS} = 0V$	-	-	-1	μA
$I_{GSS}$	Forward Gate Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 12V$	-	-	±100	nA



MU3002V

P-Channel Enhancement Mode MOSFET

## ■ On Characteristics

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = -250\mu A$	-0.5	-0.9	-1.3	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = -2.5V$ , $I_D = -2.5A$	-	50	85	$m\Omega$
		$V_{GS} = -4.5V$ , $I_D = -3.5A$	-	43	60	
		$V_{GS} = -10V$ , $I_D = -4A$	-	39	48	
$g_{fs}$	Forward Transconductance	$V_{DS} = -5V$ , $I_D = -4A$	-	19	-	S

## ■ Dynamic Characteristics

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
$C_{iss}$	Input Capacitance	$V_{DS} = -15V$ , $V_{GS} = 0V$ , $f = 1.0MHz$	-	753	-	$pF$
$C_{oss}$	Output Capacitance		-	69	-	
$C_{rss}$	Reverse Transfer Capacitance		-	59	-	

## ■ On Characteristics

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-On Delay Time	$V_{DS} = -15V$ , $R_L = 15\Omega$ , $R_G = 2.5\Omega$ , $V_{GS} = -10V$	-	4.5	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	79.5	-	
$Q_g$	Total Gate Charge	$V_{DS} = -24V$ , $I_D = -4A$ , $V_{GS} = -10V$	-	21	-	nC

## ■ Drain-Source Diode Characteristics

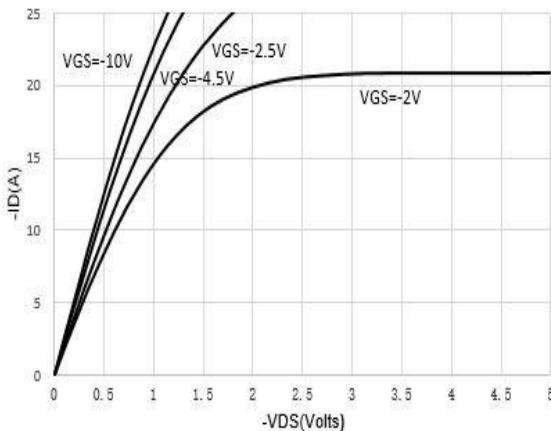
Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
$V_{SD}$	Diode Forward Voltage	$V_{GS} = 0V$ , $I_{SD} = -4.1A$	-	-0.7	-1.2	V
$I_s$	Continuous Source Current		-	-	-1.6	A

Notes:

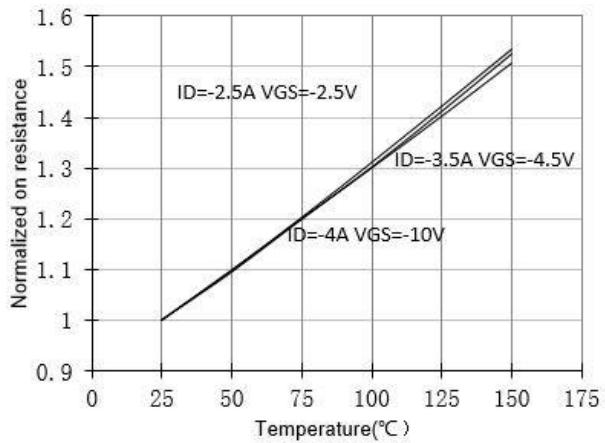
A: The value of  $R_{\theta JA}$  is measured with the device mounted on 1in2 FR-4 board with 1oz. Copper, in a still air environment with  $TA = 25^{\circ}C$ . The value in any given application depends on the user's specific board design .

B: Repetitive rating, pulse width limited by junction temperature  $TJ(MAX) = 150^{\circ}C$ . Ratings are based on low frequency and duty cycles to keep initial  $TJ = 25^{\circ}C$ .

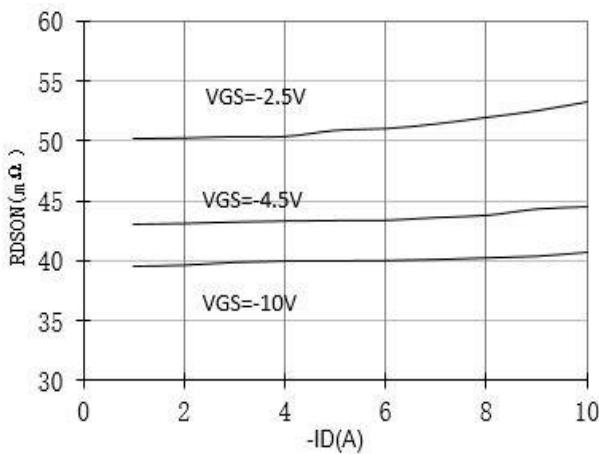
### ■ Typical Characteristics



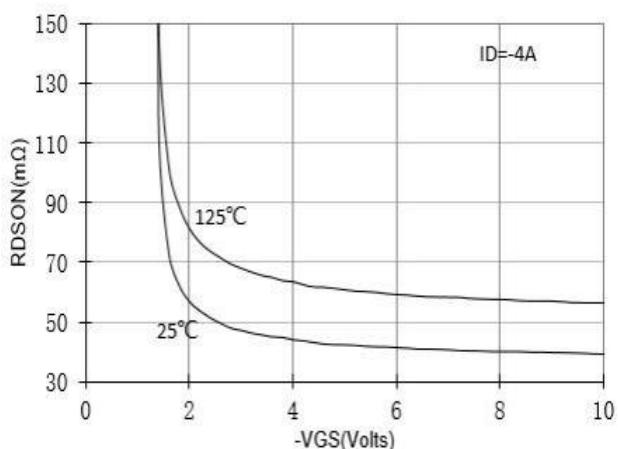
**Figure 1. Output Characteristics**



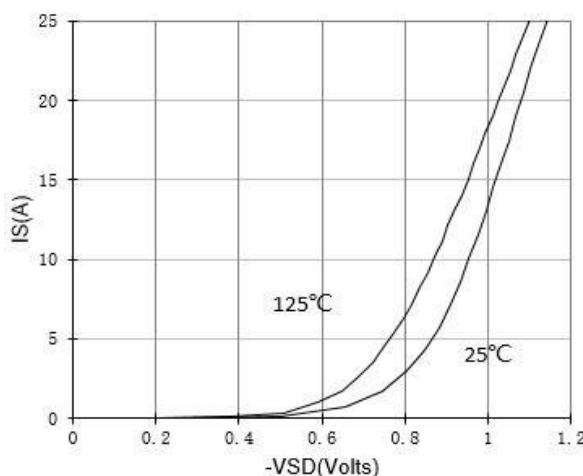
**Figure 2. On-Resistance vs. Junction Temperature**



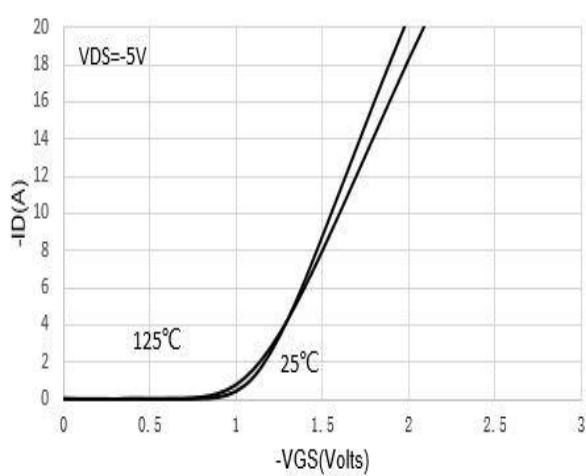
**Figure 3. On-Resistance vs. Drain Current**



**Figure 4. On-Resistance vs. Gate-Source Voltage**

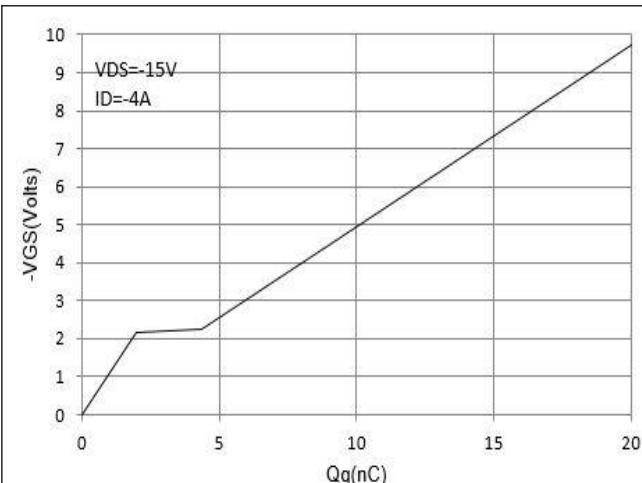


**Figure 5. Body-Diode Characteristics**

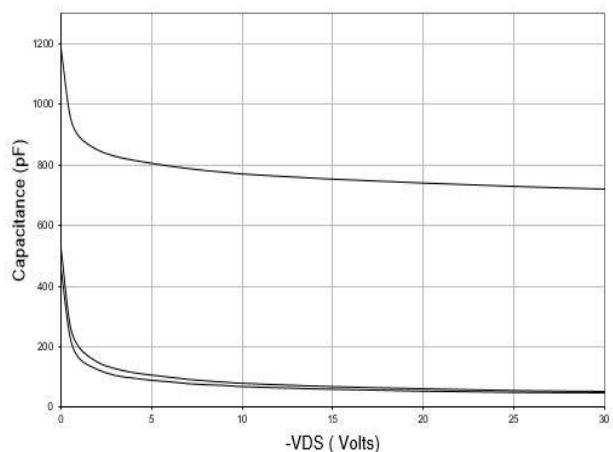


**Figure 6. Transfer Characteristics**

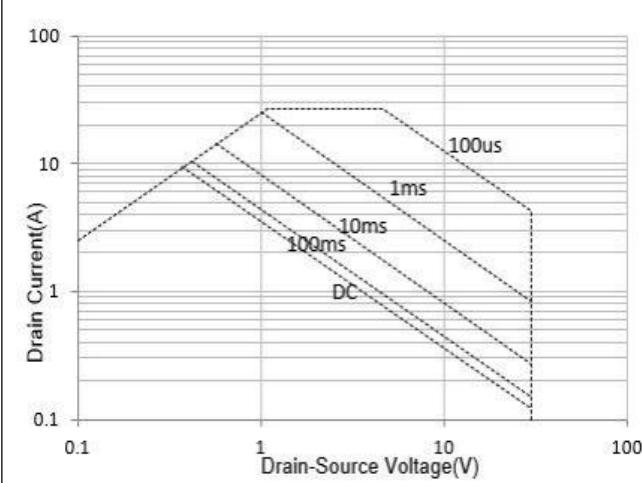
### ■ Typical Characteristics



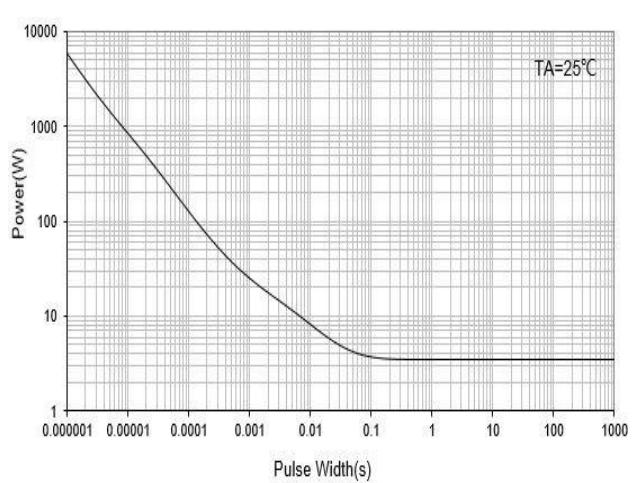
**Figure 7. Charge Characteristics**



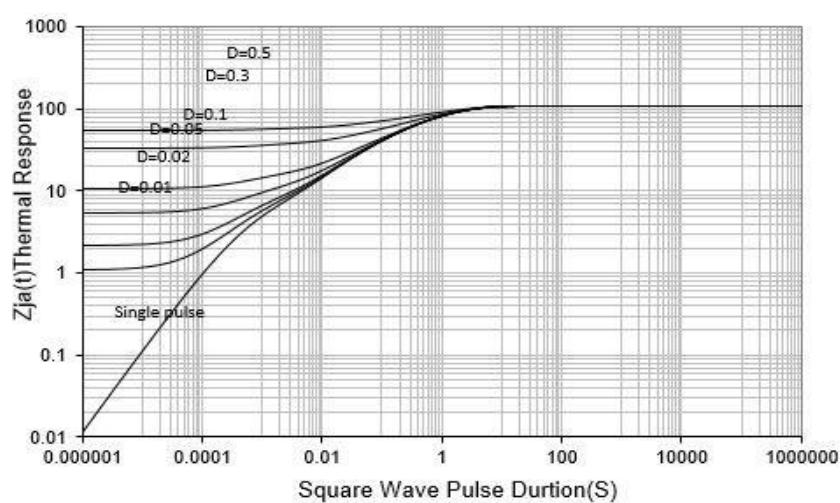
**Figure 8. Capacitance Characteristics**



**Figure 9. Maximum Forward Biased Safe Operating Area**



**Figure 10. Single Pulse Power Rating Junction-to-Ambient**



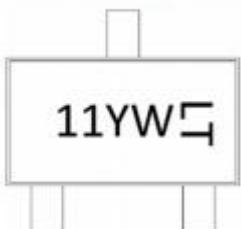
**Figure 11. Normalized Maximum Transient Thermal Impedance**



**MU3002V**  
P-Channel Enhancement Mode MOSFET

## ■ Marking Information

SOT23-3L



PN=11

YW= Date Code Marking

Y= Year W = Week

LT= Lot code